

Product Change Notification / ASER-24IAAH691

Date:

28-Jul-2020

Product Category:

8-bit Microcontrollers

PCN Type:

Manufacturing Change

Notification Subject:

CCB 3640.002 Final Notice: Qualification of MTAI as a new final test site for selected Atmel products available in 52L PLCC (19.1x19.1x4.4mm) package.

Affected CPNs:

ASER-24IAAH691_Affected_CPN_07282020.pdf ASER-24IAAH691_Affected_CPN_07282020.csv

Notification Text:

PCN Status: Final notification.

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:Qualification of MTAI as a new final test site for selected Atmel products available in 52L PLCC (19.1x19.1x4.4mm) package.

Pre Change: Tested at ATP final test site.

Post Change: Tested at MTAI final test site.

Pre and Post Change Summary:

Pre Change	Post Change
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Final Test Site	Amkor Technology Philippines (P3/P4), INC. (ATP)	Microchip Technology Thailand (HQ) MTAI			
Base Quantity Multiple (BQM)	23	23			
Pin 1 Orientation	Pin 1 facing towards black plug.	Pin 1 facing towards white plug.			
Tube Color	Clear	Clear			
Plug Color	Black	White			
Tube Dimensions	Minor dimensional changes. See pre and post change comparison.				
Packaging Process	See pre and post change comparison.				

Impacts to Data Sheet:None

Change Impact:None

Reason for Change:To improve manufacturability by qualifying MTAI as a new final test site.

Change Implementation Status: In Progress

Estimated First Ship Date: August 31, 2020 (date code: 2036)

Time Table Summary:

	July 2020				August 2020					
Workweek	2 7	2 8	2 9	3 0	3 1	32	3 3	3 4	3 5	3 6
Qual Report Availability					Х					
Final PCN Issue Date					Х					
Estimated Implementation Date										х

Method to Identify Change:Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: July 28, 2020: Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_ASER-24IAAH691_Qual_Report.pdf PCN_LIAL-05RFNS059_Packing Pre and Post Change.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our <u>PCN</u> home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections. ASER-24IAAH691 - CCB 3640.002 Final Notice: Qualification of MTAI as a new final test site for selected Atmel products available in 52L PLCC (19.1x19.1x4.4mm) package.

Affected Catalog Part Numbers (CPN)

AT89C51AC3-S3SUM AT89C51CC03UA-S3SUM AT89C51CC03CA-S3SUM AT89C5130A-S3SUM AT89C5131A-S3SUM



QUALIFICATION REPORT SUMMARY

PCN #: ASER-24IAAH691

Date: February 5, 2020

Qualification of MTAI as new final test site for selected Atmel products available in 52L PLCC (19.1x19.1x4.4mm) package.

Purpose: Qualification of MTAI as new final test site for selected Atmel products available in 52L PLCC (19.1x19.1x4.4mm) package.

CCB No.: 3640.002

Test / Evaluation	Test Conditions / Parameters	Remarks / Results
Original Final Test Site Correlation	Run 3,000 devices to the final test flows at the original site and keep the good devices and rejects in separate bins.	Passed
Destination Final Test Site Correlation	Send 3,000 tested parts to the destination test site. The results need 100% correlation to continue the release flow. Re-test the 3,000 devices from the original test site at the destination site for bin- to-bin correlation using the destination site final test program for correlation. The yield difference should be within 0.1% and bin-to-bin difference should be within 0.1%, if out of criteria then work with Product Test Engineering to determine root cause. After the results from FT were accepted, test 100% good devices to appropriate Electrical QC (EQC) program. The acceptable yield for EQC test is 100%. Any rejects will be studied by Product Test Engineering. The Final decision to accept the EQC's results must come from Product Test Engineering.	
Datalog Comparison	Collect good datalog for all flows and variants on both test program of original test site and test program of destination test site. Compare test numbers, test names, test sequence, P/F result, and test limits. Verify correct guard band is used. Accept if all parameters matched or explainable	Passed
Correlation Lot Report Correlation Lot Report Run 33 untested devices from the destination test site with same FT program; keep the good devices and rejects separate by bins and send all devices to the original test site for correlation. Re-test those 33 devices from destination test site bin- by-bin to the same FT program for correlation. The yield difference should be within 0.1% and bin-to-bin difference should be within 0.1%.		Passed
Original Final Test Site Characterization	Characterize 33 good devices at the original test site with DC items and measurable functional test items which are specified in the product datasheet (ex. Tce, Icc, Isb, Vih, Vil, Voh, Vol) and send these devices to the destination final test site.	Passed

Destination Final Test Site Characterization	Re-characterize the same 33 good devices at the destination test site using the destination site hardware/ within programs for the same DC and measurable functional test items. The results will be accepted if the variance \pm 10% of the measured values from the original test site.	Passed
50 Loop Tests with	Turn on datalog for all parametric tests. Do 50 loops test under FT test mode @ 90C. Save parametric datalog in Text and STDF files.	Passed



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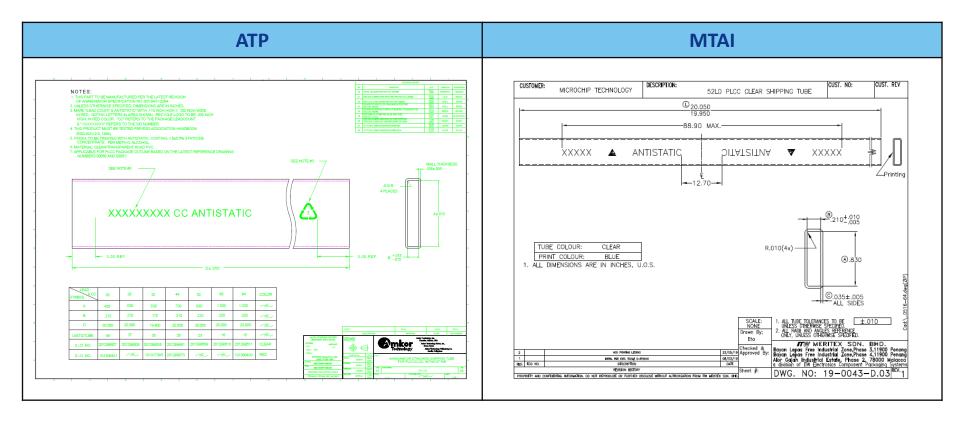


Packing Information – Tube

Packing Information	Packing Components / Media	Pre Change (ATP)	Post Change (MTAI)		
Base Quantity Multiple (BQM)	Units/Tube	23	23		
Pin 1 Orientation and Plug Color	Tube	Pin 1 facing towards black plug	Pin 1 facing towards white plug		



Packing Information – Tube Dimension



A	_	Location	Length (in)	A (in)	B (in)	Thickness (in)	Printing Color	Tube Color
	В	ATP7	20.00 +/-0.050	0.210 +0.015/-0.010	0.830 +/-0.010	0.035 +/-0.005	Red	Clear
т	-	MTAI	20.00 +/-0.050	0.210 +0.010/-0.005	0.830 +/-0.010	0.035 +/-0.005	Blue	Clear



Packing Information – Packing Method (MSL – 3)

